

2SJ221

Silicon P Channel MOS FET

REJ03G0851-0200

(Previous: ADE-208-1185)

Rev.2.00 Sep 07, 2005

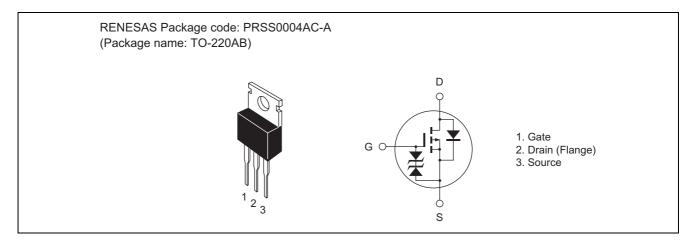
Description

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- 4 V gate drive device
 - Can be driven from 5 V source
- Suitable for motor drive, DC-DC converter, power switch and solenoid drive

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Drain to source voltage	V _{DSS}	-100	V	
Gate to source voltage	V _{GSS}	±20	V	
Drain current	I _D	-20	A	
Drain peak current	I _{D (pulse)} Note 1	-80	A	
Body to drain diode reverse drain current	I _{DR}	-20	A	
Channel dissipation	Pch Note 2	75	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at $Tc = 25^{\circ}C$

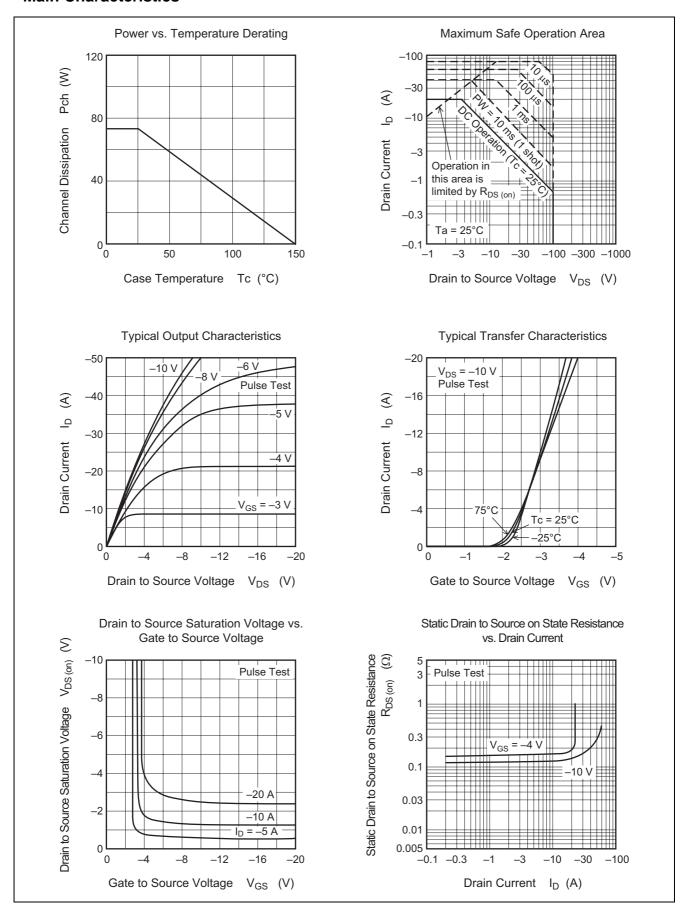
Electrical Characteristics

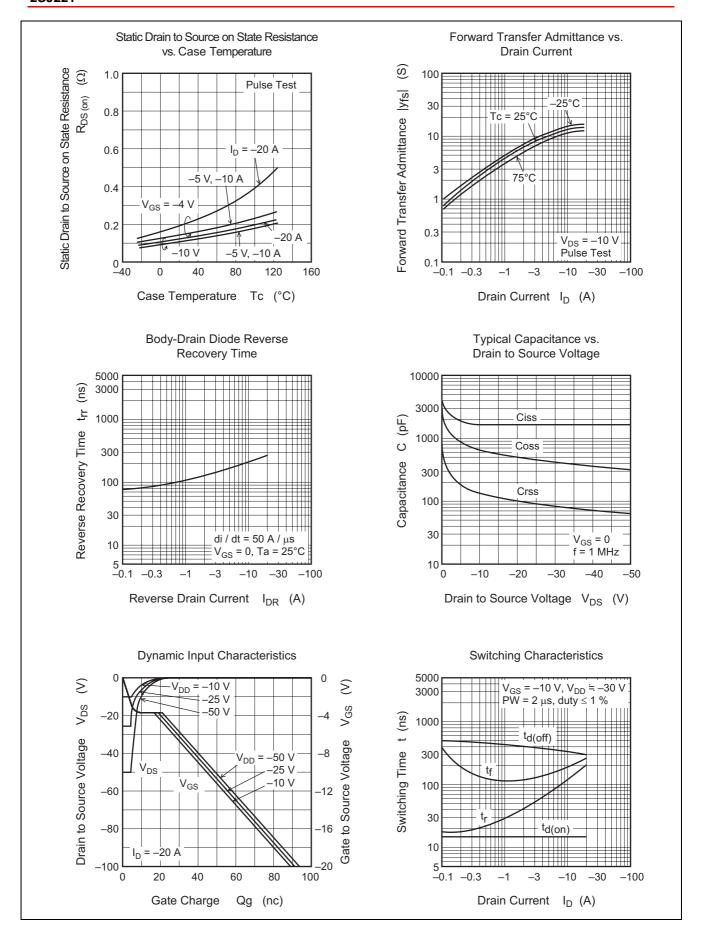
 $(Ta = 25^{\circ}C)$

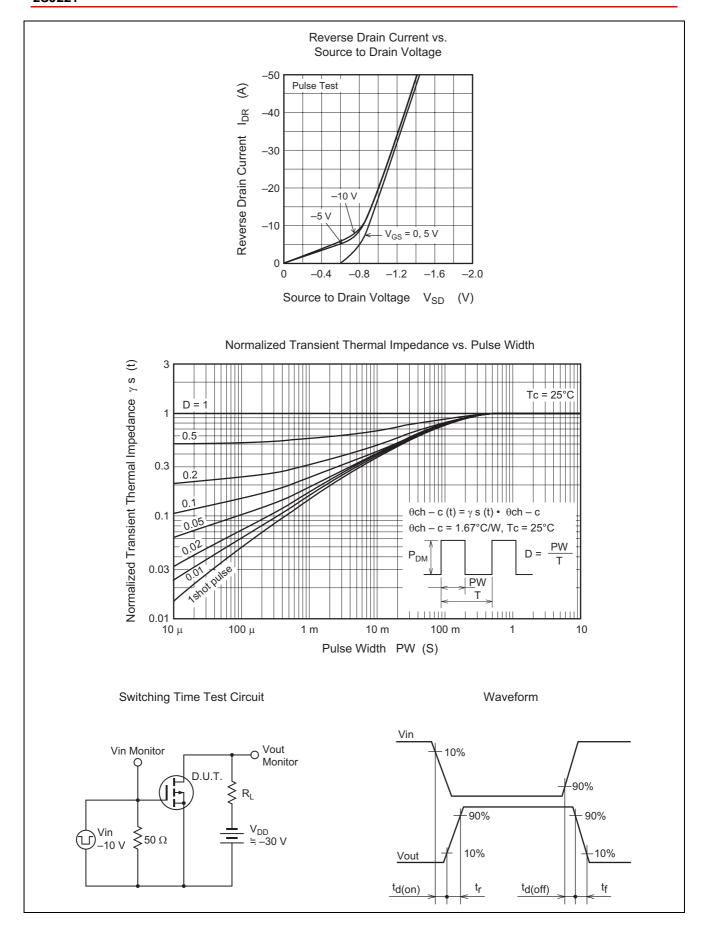
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	-100	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR) GSS}	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	-250	μΑ	$V_{DS} = -80 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-1.0	_	-2.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS (on)}	_	0.12	0.16	Ω	$I_D = -10 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 3}}$
	R _{DS (on)}	_	0.16	0.22	Ω	$I_D = -10 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	7.5	12	_	S	$I_D = -10 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	_	1800	_	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	680	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	145	_	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	15	_	ns	$I_D = -10 \text{ A}$
Rise time	t _r	_	115	_	ns	$V_{GS} = -10 \text{ V}$
Turn-off delay time	t _{d (off)}	_	320	_	ns	$R_L = 3 \Omega$
Fall time	t _f	_	170	_	ns	
Body to drain diode forward voltage	V_{DF}	_	-1.05	_	V	$I_F = -20 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	280	_	ns	$I_F = -20 \text{ A}, V_{GS} = 0$
						$di_F/dt = 50 A/\mu s$

Note: 3. Pulse test

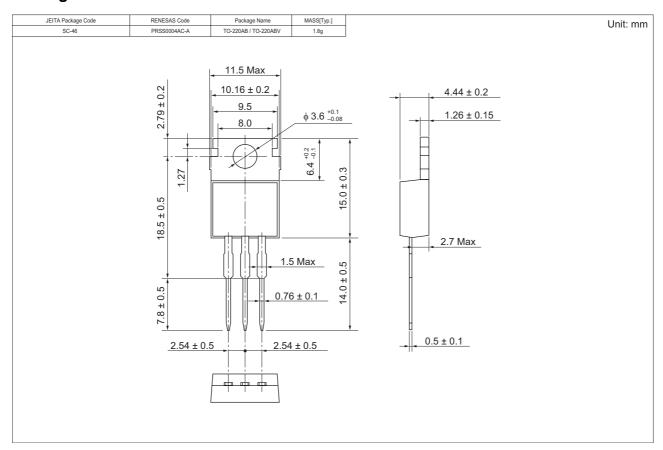
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SJ221-E	500 pcs	Box (Sack)

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